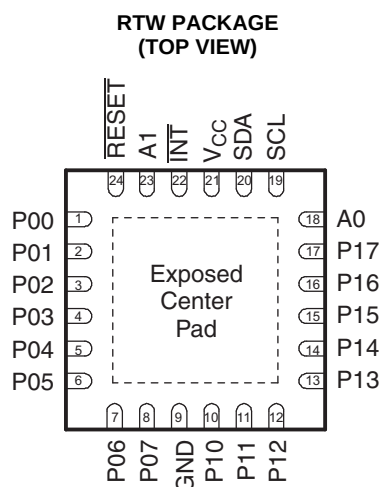
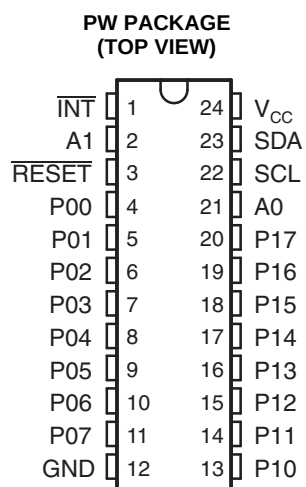


LOW VOLTAGE 16-BIT I²C I/O EXPANDER WITH INTERRUPT AND RESET

Check for Samples: [TCA1116](#)

FEATURES

- I²C to Parallel Port Expander
- Supports partial power down i.e. SDA and SCL are 5V tolerant (<1uA leakage) even when V_{CC}=0
- Supports 1.8V I²C operation
- Open-Drain Active-Low Interrupt Output
- Active-Low Reset Input
- I/O Ports are 5V tolerant
- Low Standby-Current Consumption of 3 μ A Max
- 400-kHz Fast I²C Bus support
- Polarity Inversion Register
- Configurable with up to four different I²C addresses using hardware pins
- Directly drive LEDs using high current push pull outputs
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)



The exposed center pad, if used, must be connected as a secondary ground or left electrically open.

DESCRIPTION

This 16-bit I/O expander for the two-line bidirectional bus (I²C) is designed for 1.65-V to 5.5-V V_{CC} operation. It provides general-purpose remote I/O expansion for most microcontroller families via the I²C interface [serial clock (SCL), serial data (SDA)]. Two hardware pins (A0 and A1) are used to program and vary the fixed I²C address and allow up to four devices to share the same I²C bus. The TCA1116 consists of two 8-bit Configuration (input or output selection), Input Port, Output Port, and Polarity Inversion (active-high or active-low operation) registers. At power-on, the I/Os are configured as inputs. The system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input or output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system master.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DESCRIPTION CONTINUED

The system master can reset the TCA1116 in the event of a time-out or other improper operation by asserting a low in the RESET input. The power-on reset puts the registers in their default state and initializes the I²C/SMBus state machine. Asserting RESET causes the same reset/initialization to occur without depowering the part.

The TCA1116 open-drain interrupt ($\overline{\text{INT}}$) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed.

$\overline{\text{INT}}$ can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I²C bus. Thus, the TCA1116 can remain a simple slave device.

The device outputs (latched) have high-current drive capability for directly driving LEDs. The device has low current consumption.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾ (2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – PW	Reel of 2000	TCA1116PWR	RL116
	QFN – RTW	Reel of 3000	TCA1116RTWR	RL116

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

To request a full data sheet, please send an email to:

ual_i2c@list.ti.com

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA1116PWR.A	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	See TCA1116PWR	RL116
TCA1116RTWR.A	Active	Production	WQFN (RTW) 24	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	See TCA1116RTWR	RL116

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

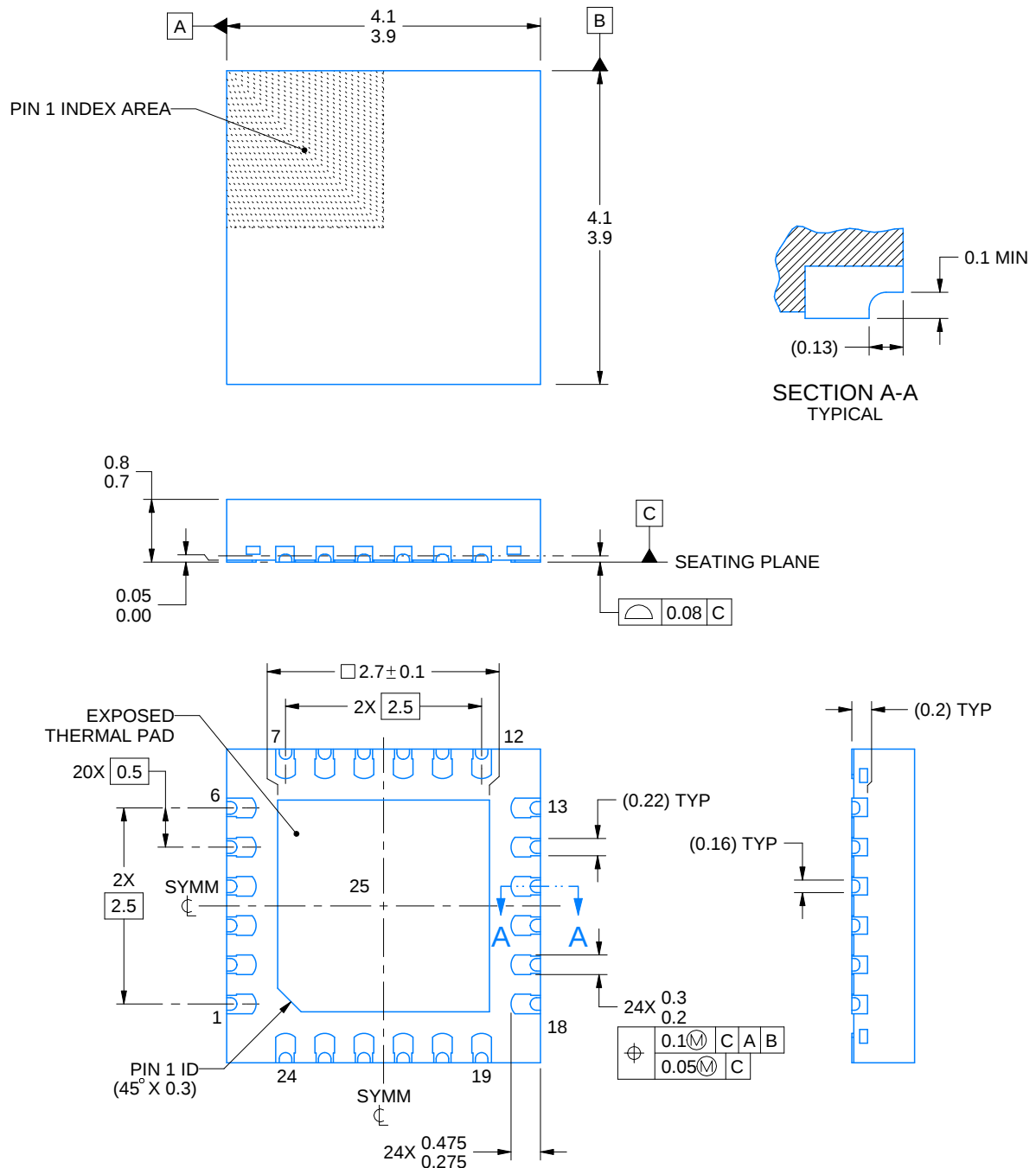
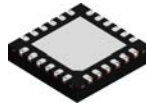
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



4232062/A 07/2025

NOTES:

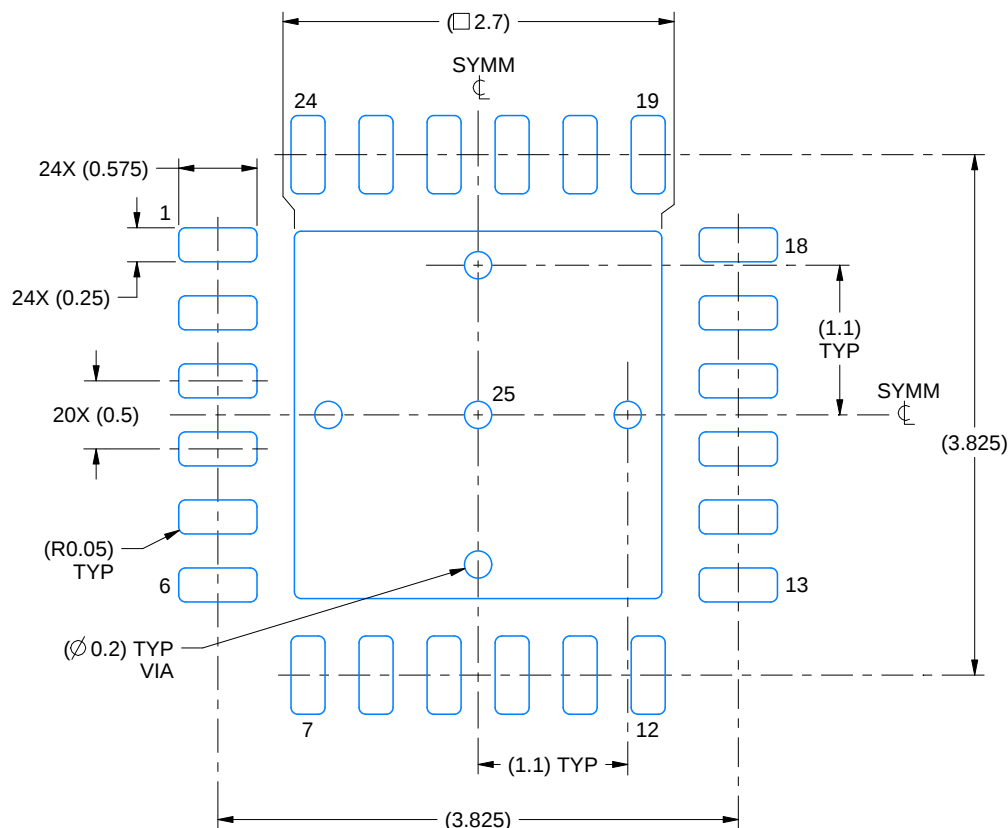
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Reference JEDEC registration MO-220.

EXAMPLE BOARD LAYOUT

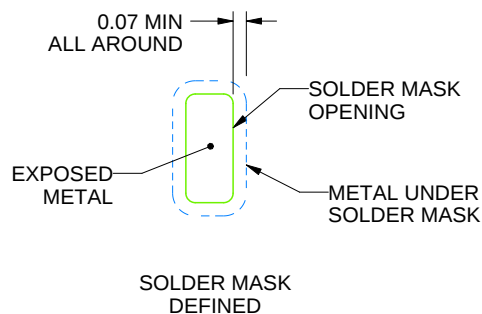
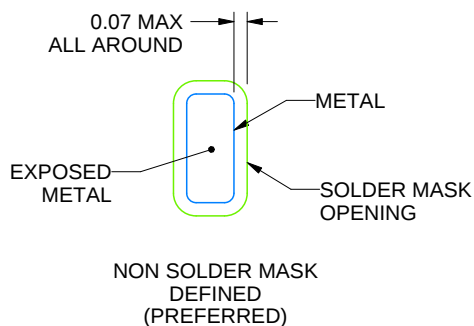
RTW0024AD

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4232062/A 07/2025

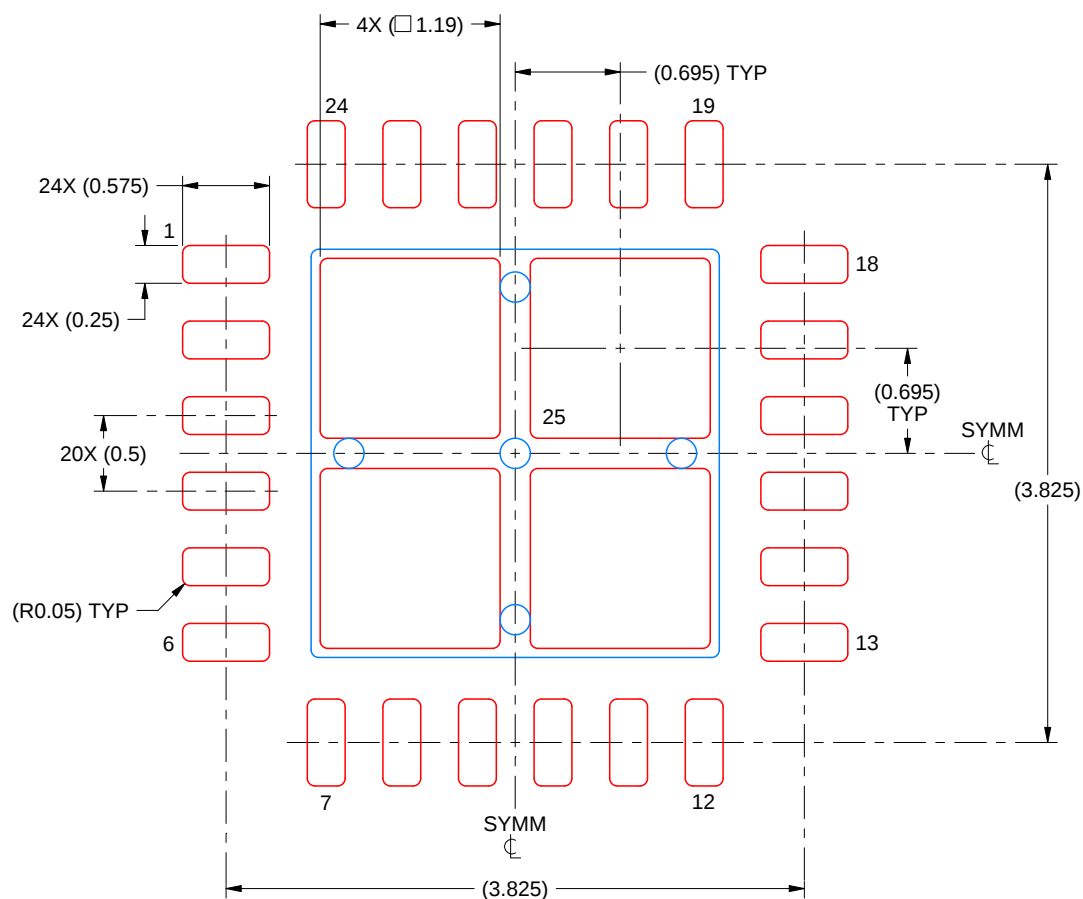
NOTES: (continued)

5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

RTW0024AD

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE

BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25

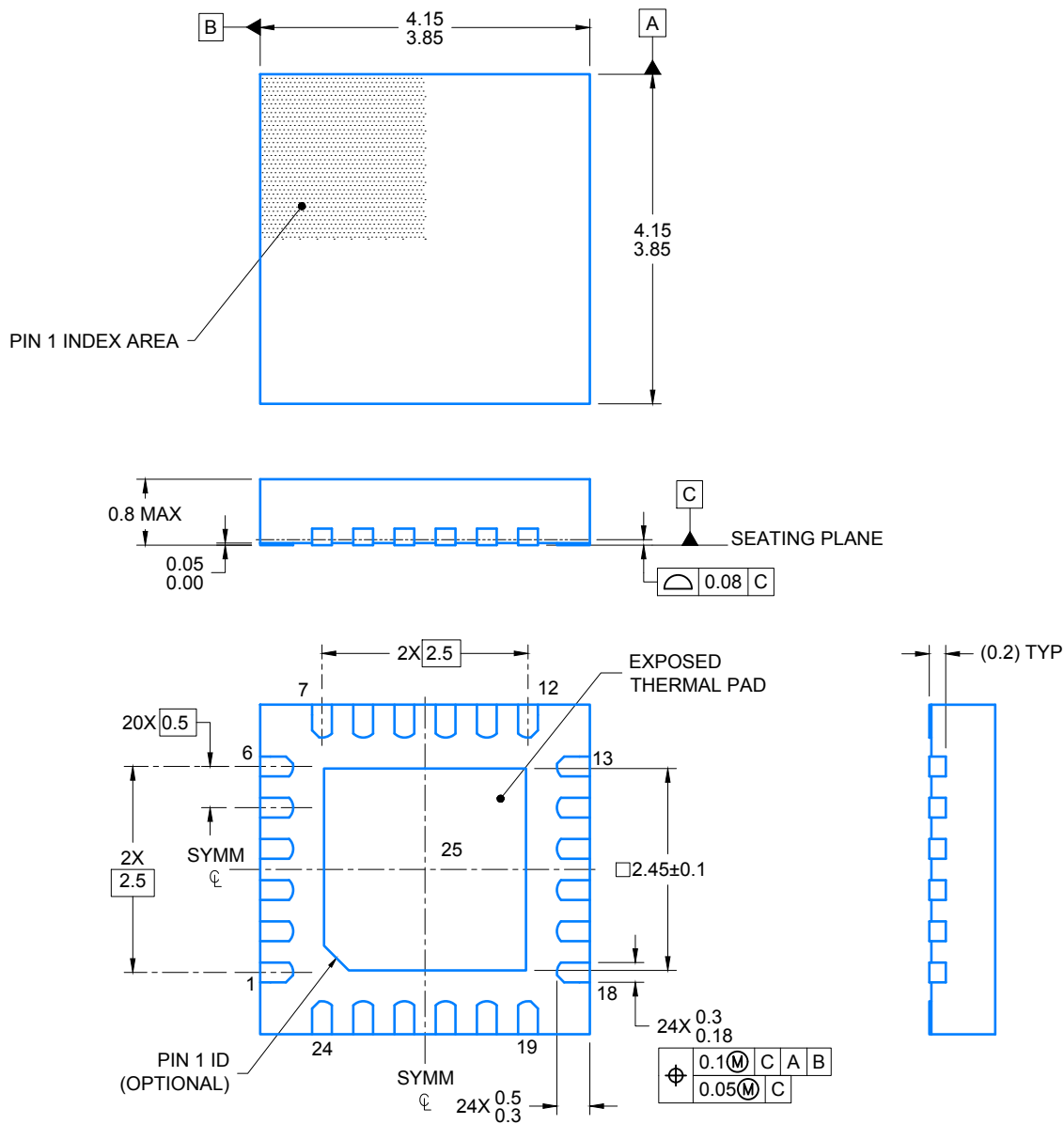
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

SCALE:20X

4232062/A 07/2025

NOTES: (continued)

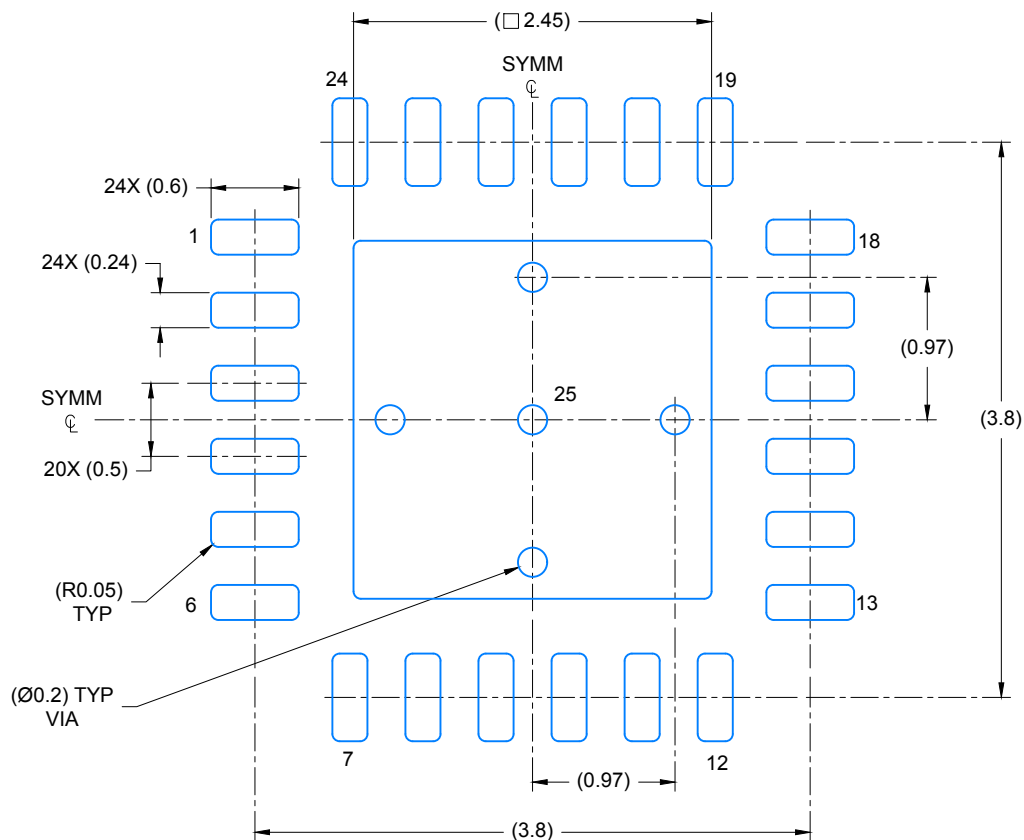
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



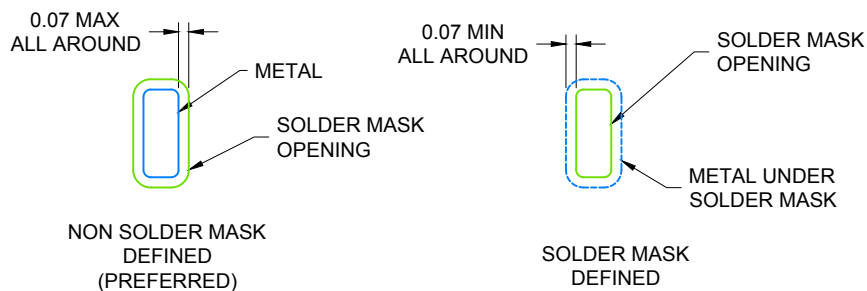
4219135/B 11/2016

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 20X

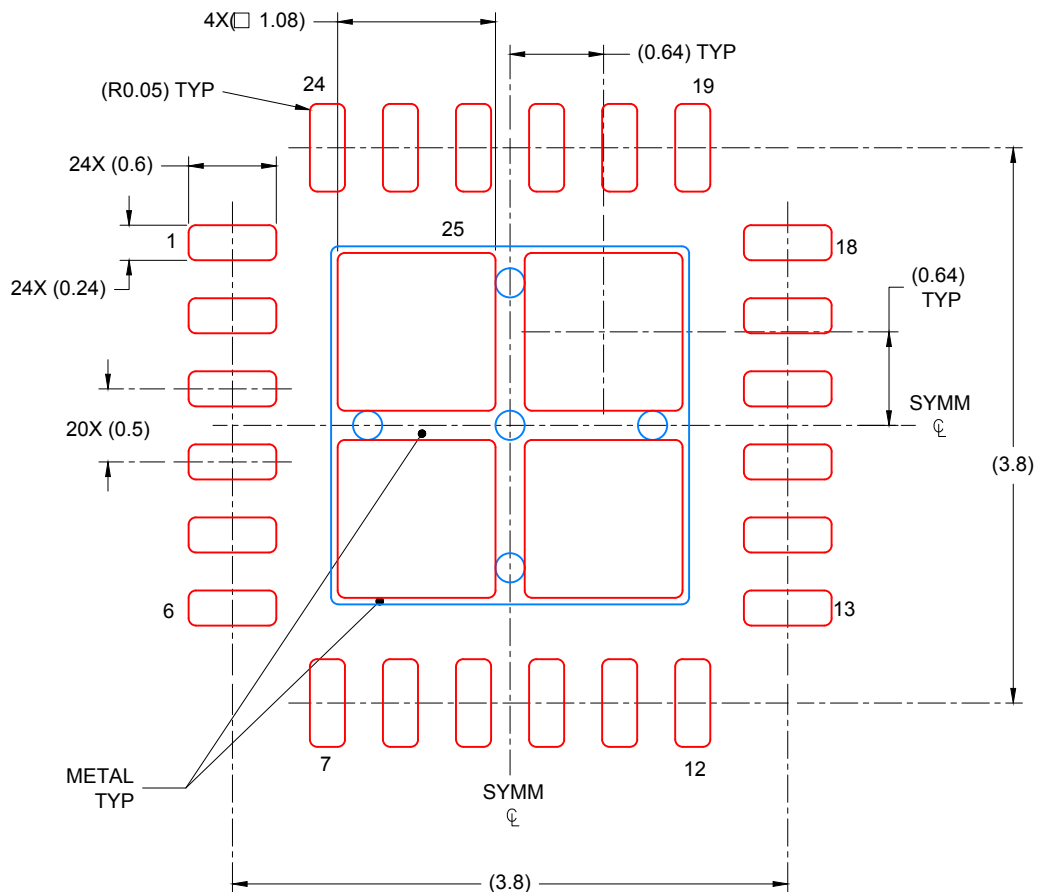


SOLDER MASK DETAILS

4219135/B 11/2016

NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:
 78% PRINTED COVERAGE BY AREA UNDER PACKAGE
 SCALE: 20X

4219135/B 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

GENERIC PACKAGE VIEW

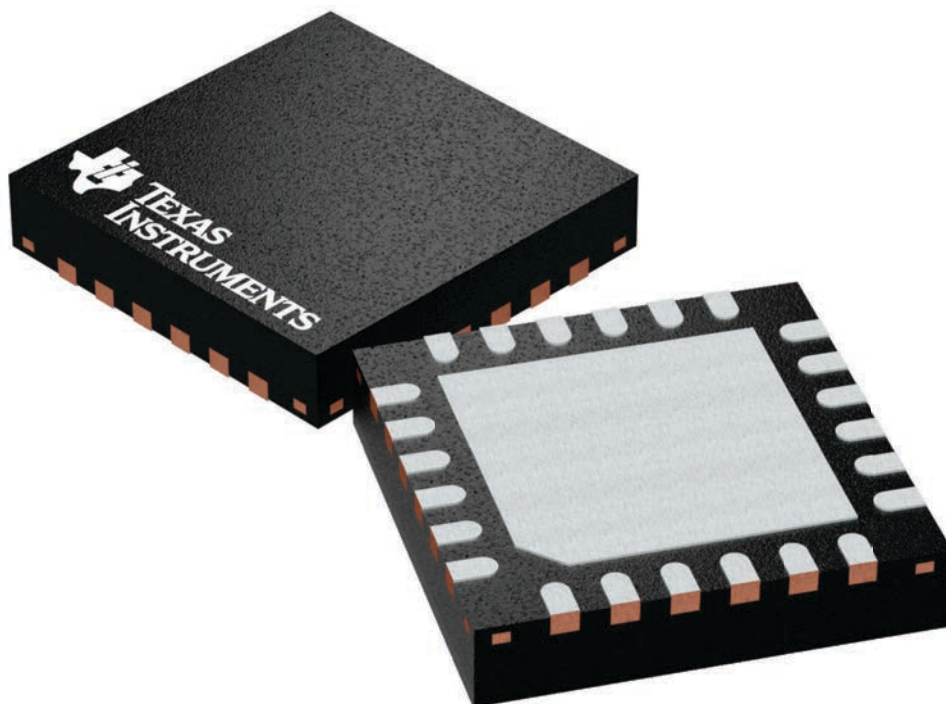
RTW 24

WQFN - 0.8 mm max height

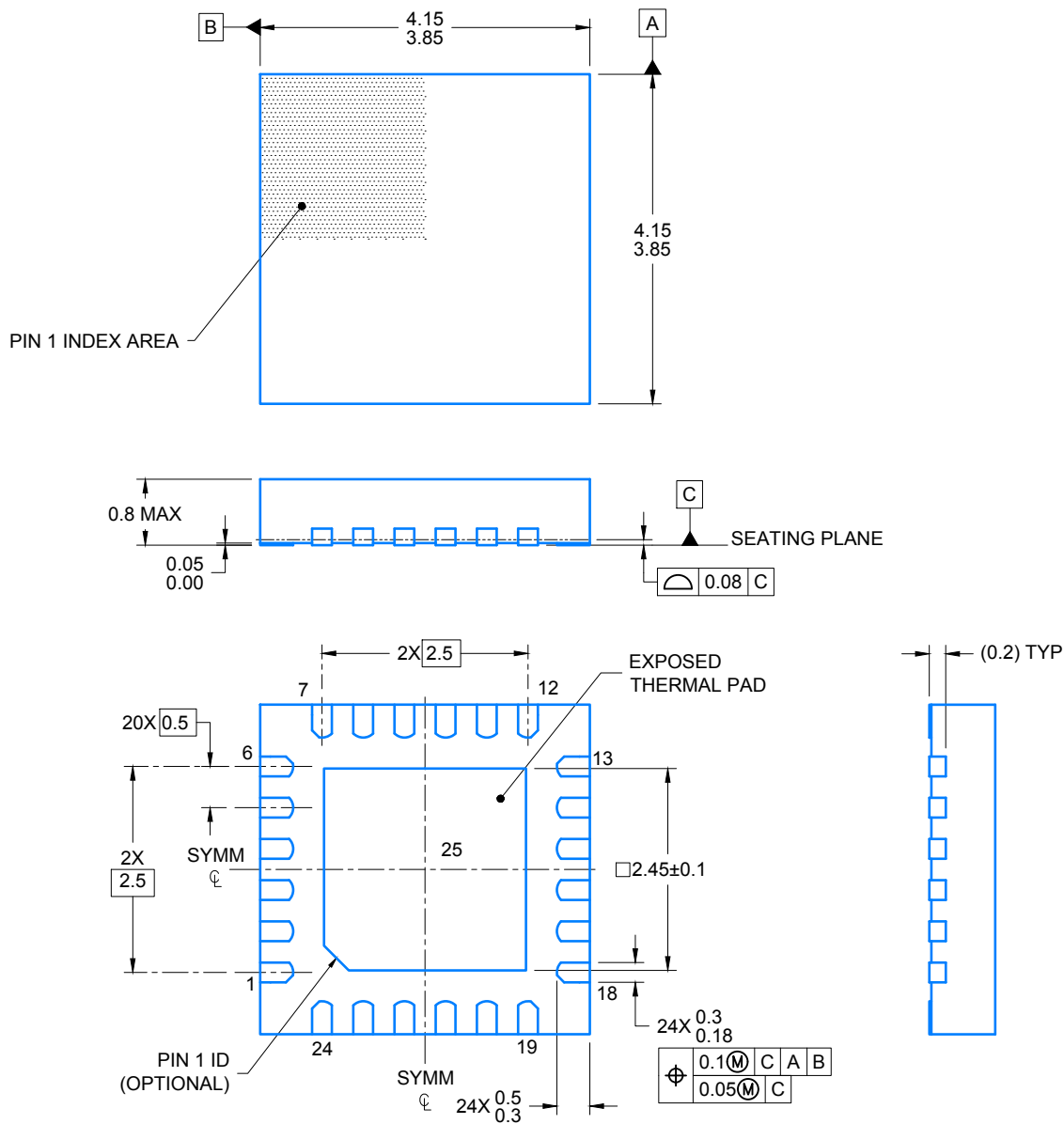
4 x 4, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



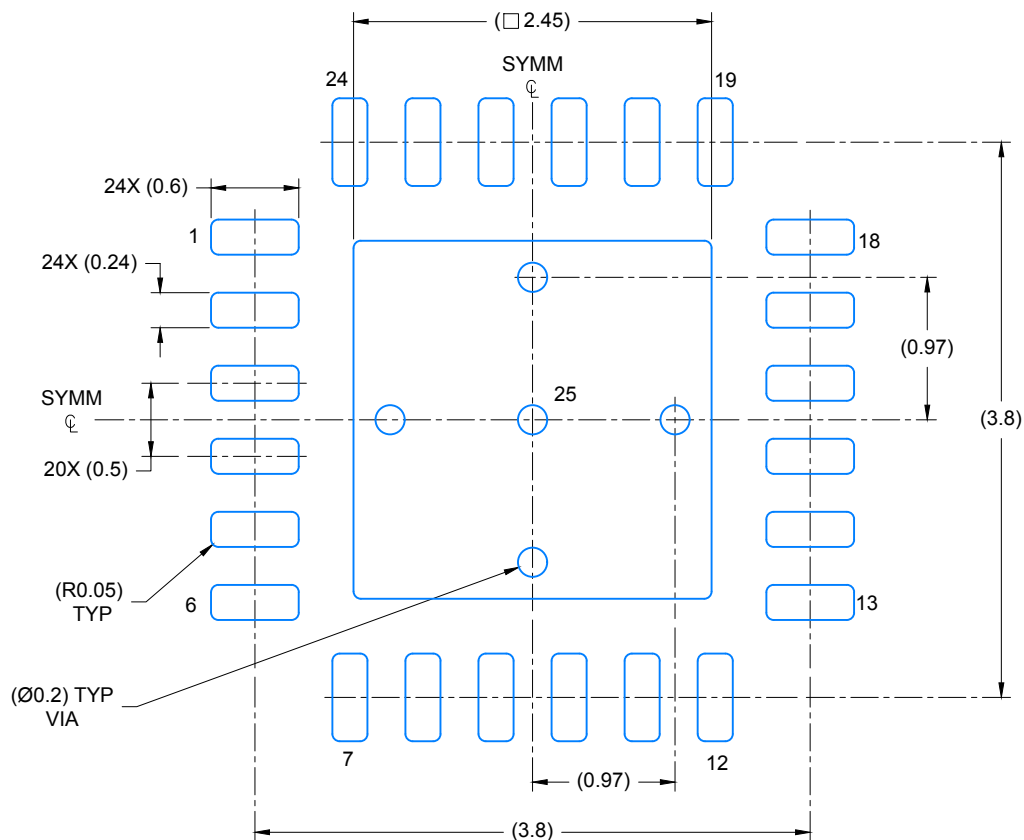
4224801/A



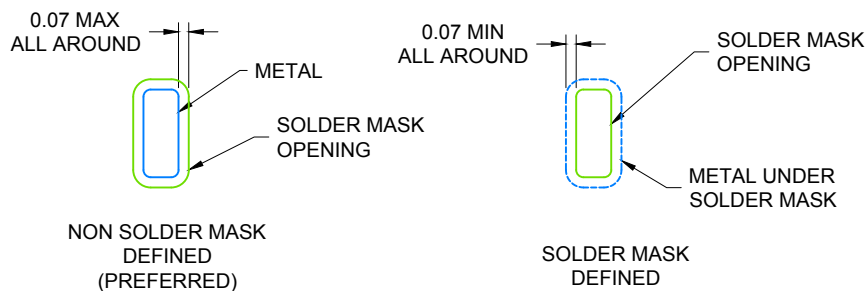
4219135/B 11/2016

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 20X

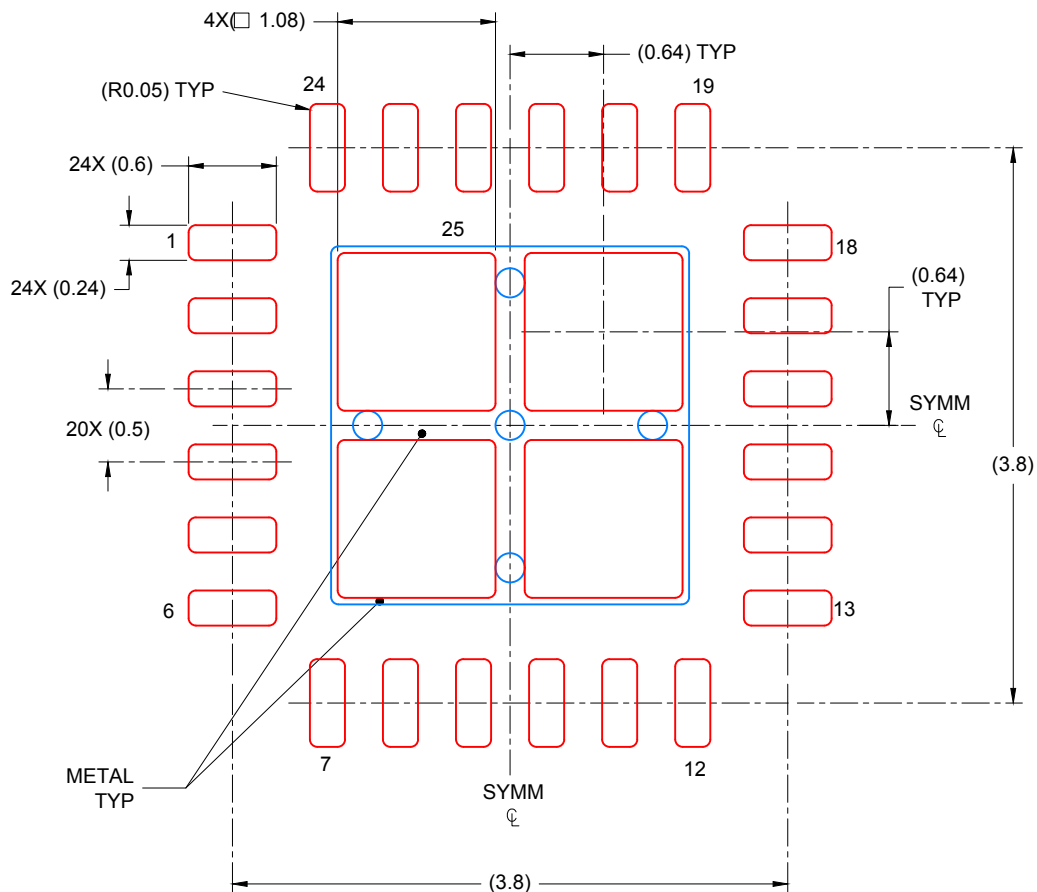


SOLDER MASK DETAILS

4219135/B 11/2016

NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:
 78% PRINTED COVERAGE BY AREA UNDER PACKAGE
 SCALE: 20X

4219135/B 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

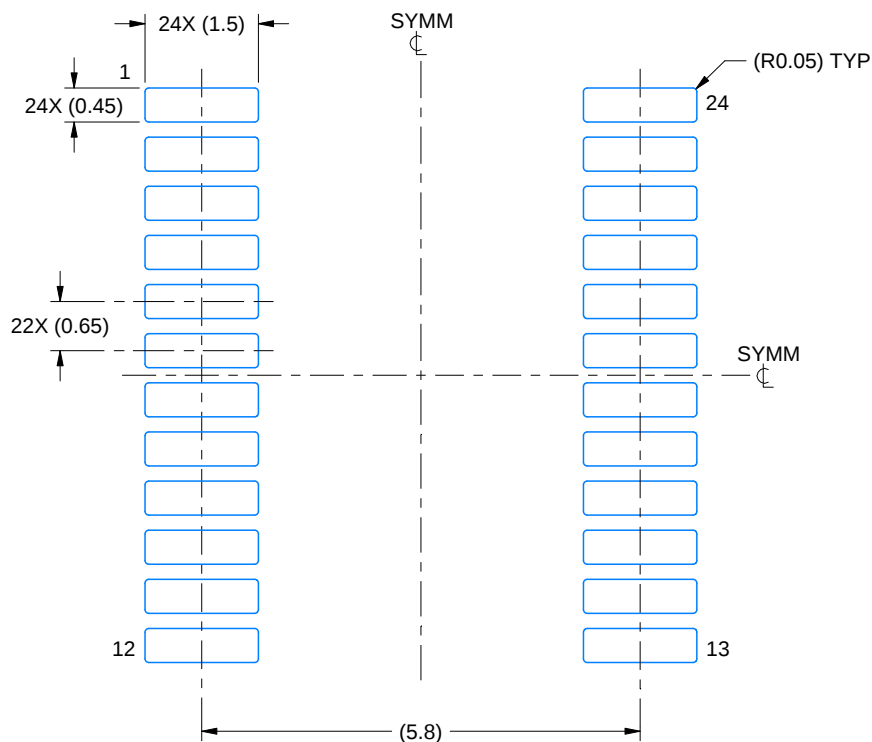


1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

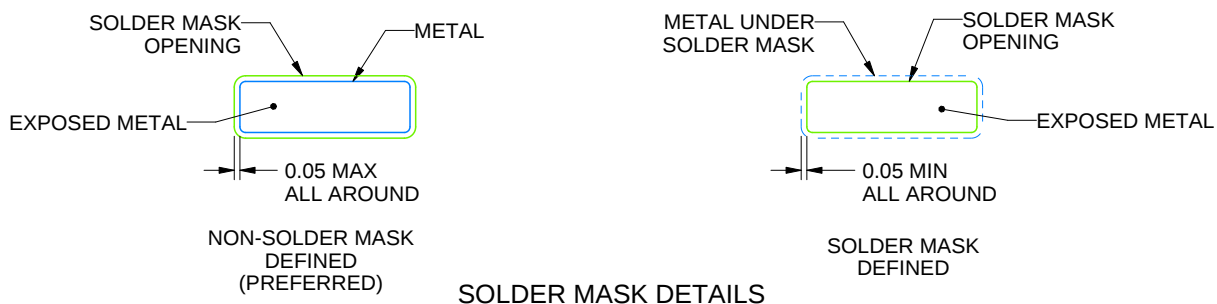
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

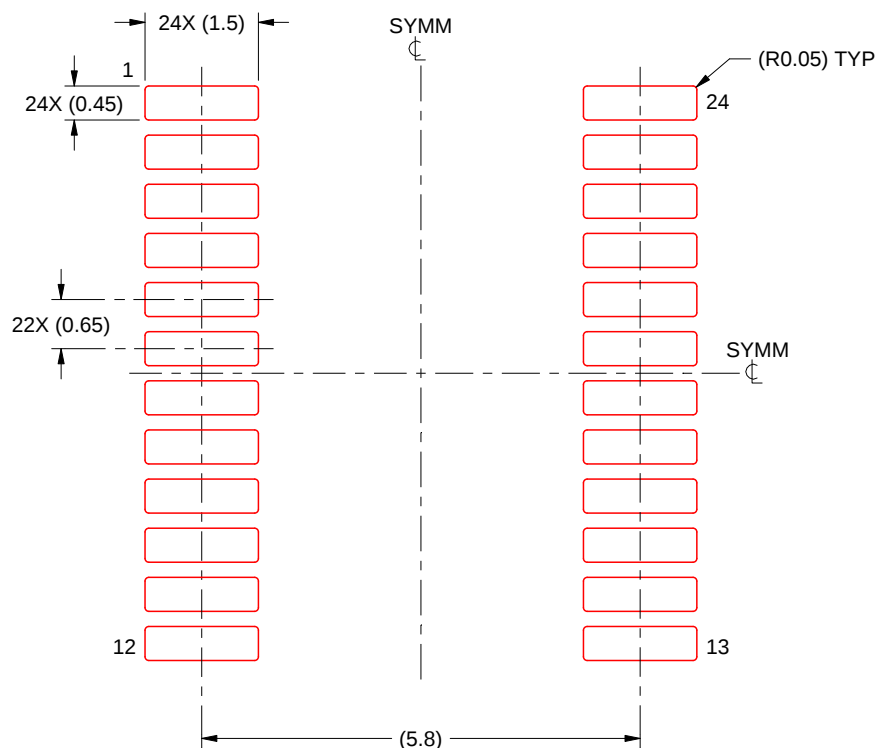
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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